VCXO Jitter Attenuator & FemtoClock™ Multiplier

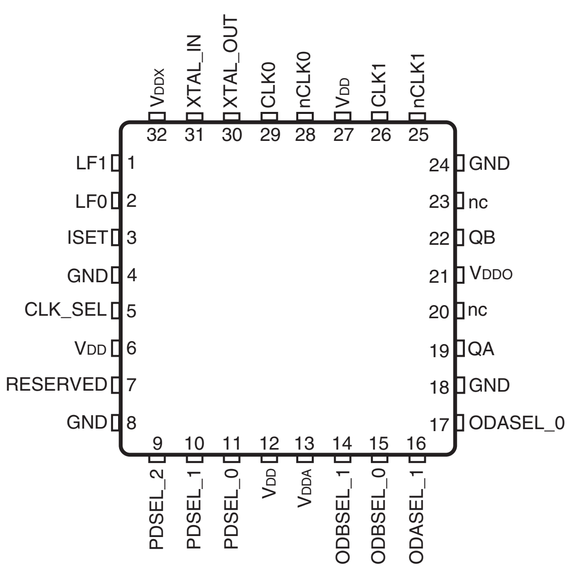
General Description

The ICS810252DI-02 is a PLL based synchronous multiplier that is optimized for PDH or SONET to Ethernet clock jitter attenuation and frequency translation. The device contains two internal frequency multiplication stages that are cascaded in series. The first stage is a VCXO PLL that is optimized to provide reference clock jitter attenuation. The second stage is a FemtoClock™ frequency multiplier that provides the low jitter, high frequency Ethernet output clock that easily meets Gigabit and 10 Gigabit Ethernet jitter requirements. Pre-divider and output divider multiplication ratios are selected using device selection control pins. The multiplication ratios are optimized to support most common clock rates used in PDH, SONET and Ethernet applications. The VCXO requires the use of an external, inexpensive pullable crystal. The VCXO uses external passive loop filter components which allows configuration of the PLL loop bandwidth and damping characteristics. The device is packaged in a space-saving 32-VFQFN package and supports industrial temperature range.

Features

- Two LVCMOS/LVTTL outputs, 14Ω output impedance
  Each output supports independent frequency selection at 25MHz, 125MHz, 156.25MHz and 312.5MHz
- Two differential input pairs support the following input types: LVPECL, LVDS, LVHSTL, SSTL, HCSL
- Accepts input frequencies from: 8kHz to 155.52MHz including 8kHz, 1.544MHz, 2.048MHz, 19.44MHz, 25MHz, 77.76MHz, 125MHz and 155.52MHz
- Attenuates the phase jitter of the input clock by using a low-cost pullable fundamental mode VCXO crystal
- VCXO PLL bandwidth can be optimized for jitter attenuation and reference tracking using external loop filter connection
- FemtoClock frequency multiplier provides low jitter, high frequency output
- Absolute pull range: ±50ppm
- FemtoClock VCO frequency: 625MHz
- RMS phase jitter @ 125MHz, using a 25MHz crystal (10kHz – 20MHz): 1.3ps (maximum)
- 3.3V supply voltage
- -40°C to 85°C ambient operating temperature
- Available in lead-free (RoHS 6) package

Pin Assignment



ICS810252DI-02
32 Lead VFQFN
5mm x 5mm x 0.925mm package body
K Package
Top View

Block Diagram

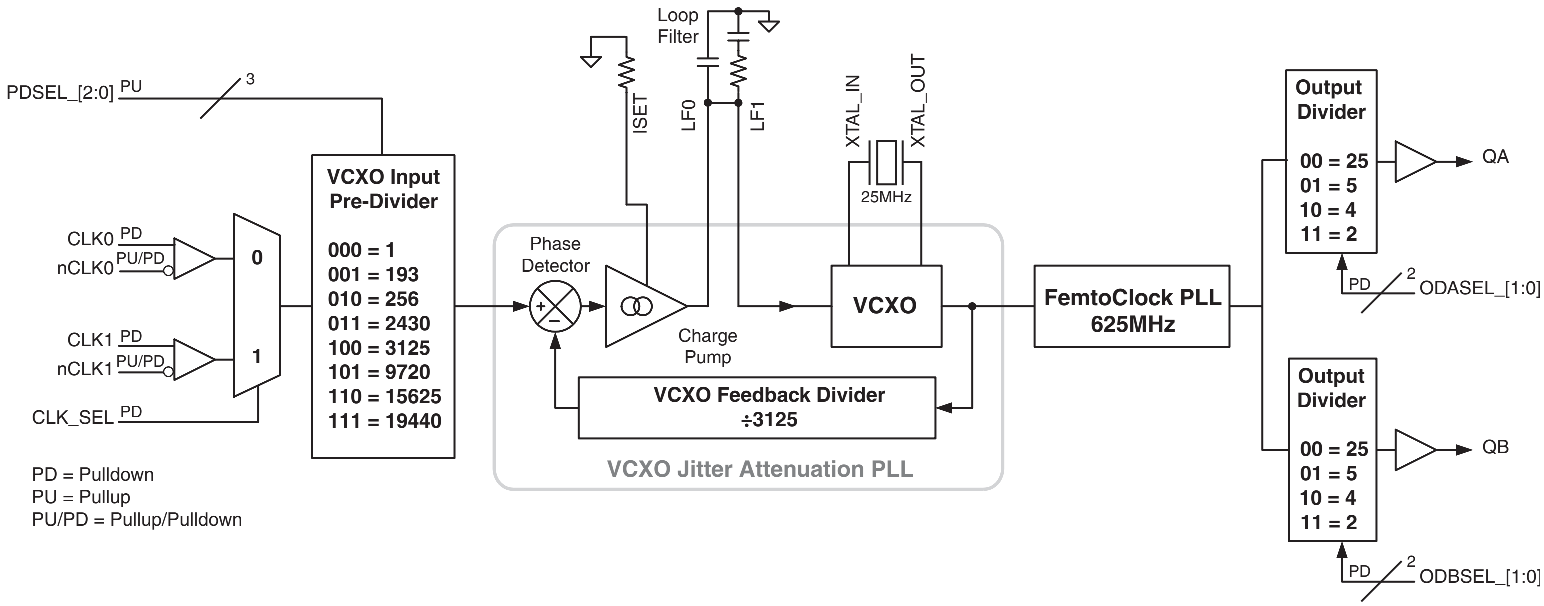


Table 1. Pin Descriptions

Number	Name	Type		Description
1, 2	LF1, LF0	Analog Input/Output		Loop filter connection node pins. LF0 is the output. LF1 is the input.
3	ISET	Analog Input/Output		Charge pump current setting pin.
4, 8, 18, 24	GND	Power		Power supply ground.
5	CLK_SEL	Input	Pulldown	Input clock select. When HIGH selects CLK1/nCLK1. When LOW, selects CLK0/nCLK0. LVCMOS / LVTTL interface levels.
6, 12, 27	V_{DD}	Power		Core supply pins.
7	RESERVED	Reserved		Reserved pin. Do not connect.
9, 10, 11	PDSEL_2, PDSEL_1, PDSEL_0	Input	Pullup	Pre-divider select pins. LVCMOS/LVTTL interface levels. See Table 3A.
13	V_{DDA}	Power		Analog supply pin.
14, 15	ODBSEL_1, ODBSEL_0	Input	Pulldown	Frequency select pin for Bank B output. See Table 3B. LVCMOS/LVTTL interface levels.
16, 17	ODASEL_1, ODASEL_0	Input	Pulldown	Frequency select pin for Bank A output. See Table 3B. LVCMOS/LVTTL interface levels.
19	QA	Output		Single-ended Bank A clock output. LVCMOS/LVTTL interface levels.
20, 23	nc	Unused		No connect.
21	V_{DDO}	Power		Output supply pin.
22	QB	Output		Single-ended Bank B clock output. LVCMOS/LVTTL interface levels.
25	nCLK1	Input	Pullup/ Pulldown	Inverting differential clock input. $V_{DD}/2$ bias voltage when left floating.
26	CLK1	Input	Pulldown	Non-inverting differential clock input.
28	nCLK0	Input	Pullup/ Pulldown	Inverting differential clock input. $V_{DD}/2$ bias voltage when left floating.
29	CLK0	Input	Pulldown	Non-inverting differential clock input.
30, 31	XTAL_OUT, XTAL_IN	Input		Crystal oscillator interface. XTAL_IN is the input. XTAL_OUT is the output.
32	V_{DDX}	Power		Power supply pin for VCXO charge pump.

NOTE: *Pullup and Pulldown* refer to internal input resistors. See Table 2, *Pin Characteristics,* for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C_{IN}	Input Capacitance			4		pF
C_{PD}	Power Dissipation Capacitance (per output)	$V_{DD} = V_{DDX} = V_{DDO} = 3.465V$		9	12	pF
R_{PULLUP}	Input Pullup Resistor			51		kΩ
$R_{PULLDOWN}$	Input Pulldown Resistor			51		kΩ
R_{OUT}	Output Impedance			14		Ω

Function Tables

Table 3A. Pre-Divider Selection Function Table

Inputs			
PDSEL_2	PDSEL_1	PDSEL_0	Pre-Divider Value
0	0	0	1
0	0	1	193
0	1	0	256
0	1	1	2430
1	0	0	3125
1	0	1	9720
1	1	0	15625
1	1	1	19440 (default)

Table 3B. Output Divider Function Table

Inputs		
ODxSEL_1	ODxSEL_0	Output Divider Value
0	0	25 (default)
0	1	5
1	0	4
1	1	2

Table 3C. Frequency Function Table

Input Frequency (MHz)	Pre-Divider Value	VCXO Frequency (MHz)	FemtoClock Feedback Divider Value	FemtoClock VCO Frequency (MHz)	Output Divider Value	Output Frequency (MHz)
0.008	1	25	25	625	25	25
0.008	1	25	25	625	5	125
0.008	1	25	25	625	4	156.25
0.008	1	25	25	625	2	312.5
1.544	193	25	25	625	25	25
1.544	193	25	25	625	5	125
1.544	193	25	25	625	4	156.25
1.544	193	25	25	625	2	312.5
2.048	256	25	25	625	25	25
2.048	256	25	25	625	5	125
2.048	256	25	25	625	4	156.25
2.048	256	25	25	625	2	312.5
19.44	2430	25	25	625	25	25
19.44	2430	25	25	625	5	125
19.44	2430	25	25	625	4	156.25
19.44	2430	25	25	625	2	312.5
25	3125	25	25	625	25	25
25	3125	25	25	625	5	125
25	3125	25	25	625	4	156.25
25	3125	25	25	625	2	312.5
77.76	9720	25	25	625	25	25
77.76	9720	25	25	625	5	125
77.76	9720	25	25	625	4	156.25
77.76	9720	25	25	625	2	312.5
125	15625	25	25	625	25	25
125	15625	25	25	625	5	125
125	15625	25	25	625	4	156.25
125	15625	25	25	625	2	312.5
155.52	19440	25	25	625	25	25
155.52	19440	25	25	625	5	125
155.52	19440	25	25	625	4	156.25
155.52	19440	25	25	625	2	312.5

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics or AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V_{DD}	4.6V
Inputs, V_I XTAL_IN Other Inputs	 0V to V_{DD} -0.5V to V_{DD} + 0.5V
Outputs, V_O	-0.5V to V_{DD} + 0.5V
Package Thermal Impedance, θ_{JA}	37°C/W (0 mps)
Storage Temperature, T_{STG}	-65°C to 150°C

DC Electrical Characteristics

Table 4A. Power Supply DC Characteristics, $V_{DD} = V_{DDO} = V_{DDX} = 3.3V \pm 5\%$, T_A = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{DD}	Core Supply Voltage		3.135	3.3	3.465	V
V_{DDA}	Analog Supply Voltage		V_{DD} – 0.15	3.3	V_{DD}	V
V_{DDO}	Output Supply Voltage		3.135	3.3	3.465	V
V_{DDX}	Charge Pump Supply Voltage		3.135	3.3	3.465	V
I_{DD} + I_{DDX}	Power Supply Current				206	mA
I_{DDA}	Analog Supply Current				15	mA
I_{DDO}	Output Supply Current	No Load			3	mA

Table 4B. LVCMOS/LVTTL DC Characteristics, $V_{DD} = V_{DDO} = V_{DDX} = 3.3V \pm 5\%$, T_A = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage			2		V_{DD} + 0.3	V
V_{IL}	Input Low Voltage			-0.3		0.8	V
I_{IH}	Input High Current	CLK_SEL, ODASEL_[1:0], ODBSEL_[1:0]	$V_{DD} = V_{IN} = 3.465V$			150	µA
		PDSEL[2:0]	$V_{DD} = V_{IN} = 3.465V$			5	µA
I_{IL}	Input Low Current	CLK_SEL, ODASEL_[1:0], ODBSEL_[1:0]	$V_{DD} = 3.465V$, $V_{IN} = 0V$	-5			µA
		PDSEL[2:0]	$V_{DD} = 3.465$, $V_{IN} = 0V$	-150			µA
V_{OH}	Output High Voltage; NOTE 1			2.6			V
V_{OL}	Output Low Voltage; NOTE 1					0.5	V

NOTE 1: Outputs terminated with 50Ω to $V_{DDO}/2$. See Parameter Measurement Information section. *Load Test Circuit diagrams.*

Table 4C. Differential DC Characteristics, $V_{DD} = V_{DDO} = V_{DDX} = 3.3V \pm 5\%$, $T_A = -40°C$ to $85°C$

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
I_{IH}	Input High Current	CLK0/nCLK0, CLK1/nCLK1	$V_{DD} = V_{IN} = 3.465V$			150	µA
I_{IL}	Input Low Current	CLK0, CLK1	$V_{DD} = 3.465V$, $V_{IN} = 0V$	-5			µA
		nCLK0, nCLK1	$V_{DD} = 3.465V$, $V_{IN} = 0V$	-150			µA
V_{PP}	Peak-to-Peak Input Voltage			0.15		1.3	V
V_{CMR}	Common Mode Input Voltage; NOTE 1			GND + 0.5		V_{DD} – 0.85	V

NOTE 1: Common mode voltage is defined as V_{IH}.

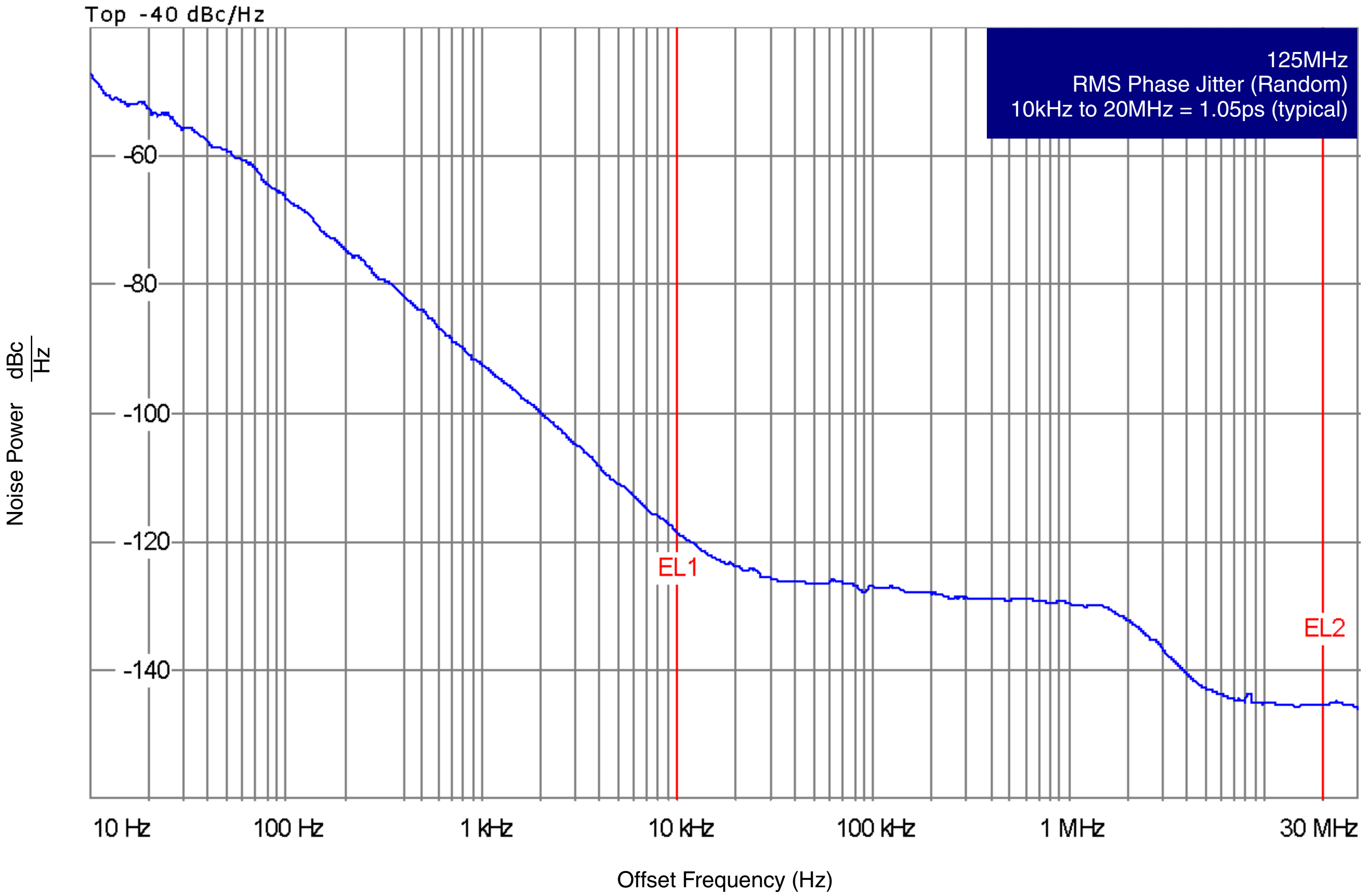
AC Electrical Characteristics

Table 5. AC Characteristics, $V_{DD} = V_{DDO} = V_{DDX} = 3.3V \pm 5\%$, $T_A = -40°C$ to $85°C$

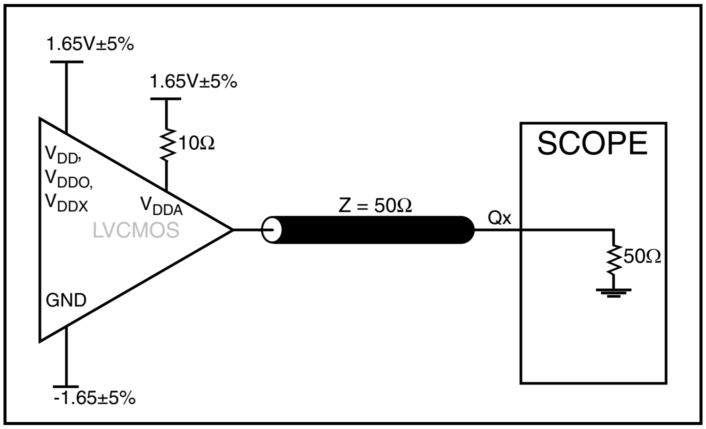
Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{IN}	Input Frequency		0.008		155.52	MHz
f_{OUT}	Output Frequency		25		312.5	MHz
*t*jit(Ø)	RMS Phase Jitter, (Random), NOTE 1, 2	125MHz f_{OUT}, 25MHz crystal, Integration Range: 10kHz – 20MHz		1.05	1.3	ps
*t*sk(o)	Output Skew; NOTE 3, 4				200	ps
odc	Output Duty Cycle	$f_{OUT} \leq 156.25MHz$	45		55	%
t_R / t_F	Output Rise/Fall Time	20% to 80%	200		800	ps
t_{LOCK}	VCXO & FemtoClock PLL Lock Time; NOTE 5	Reference Clock Input is ±50ppm from Nominal Frequency			2.5	S

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.
NOTE: Characterized with outputs at the same frequency using the loop filter components for the mid loop bandwidth. Refer to VCXO-PLL *Loop Bandwidth Selection Table*.
NOTE 1: Refer to the Phase Noise Plot.
NOTE 2: Not tested in production.
NOTE 3: This parameter is defined in accordance with JEDEC Standard 65.
NOTE 4: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at $V_{DDO}/2$.
NOTE 5: Lock Time measured from power-up to stable output frequency.

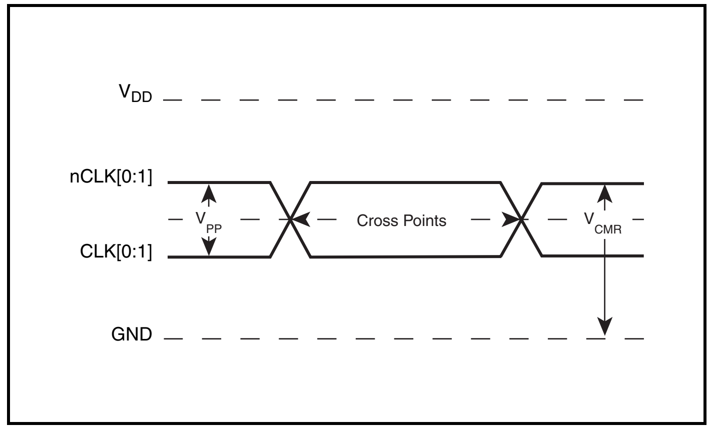
Typical Phase Noise at 125MHz



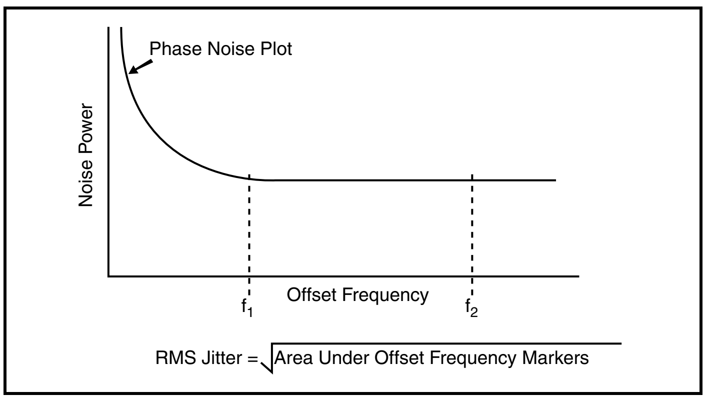
Parameter Measurement Information



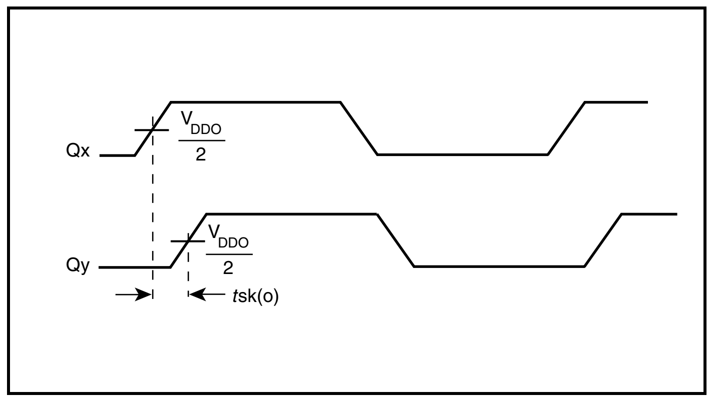
3.3V Output Load AC Test Circuit



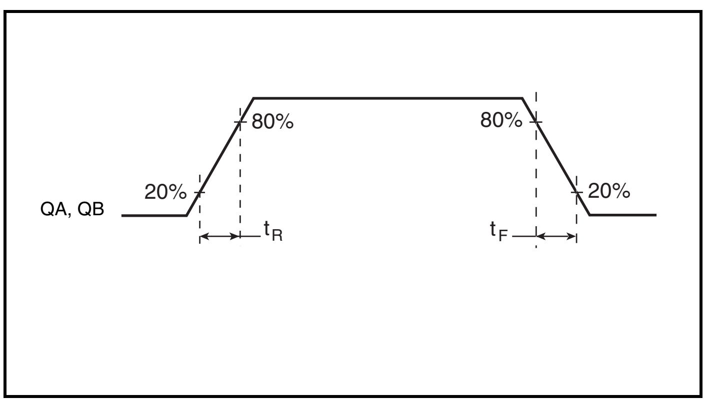
Differential Input Level



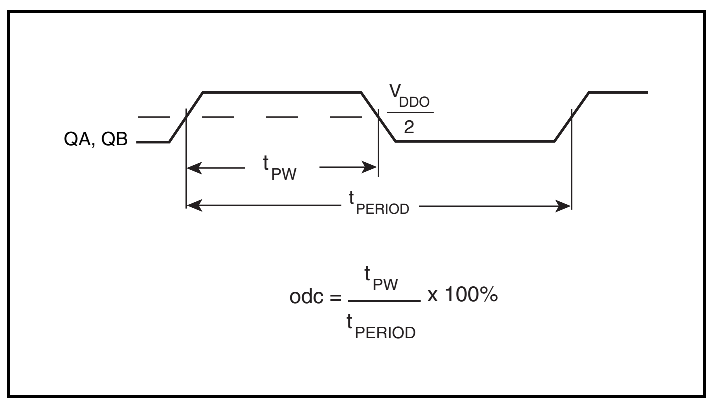
RMS Phase Jitter



Output Skew

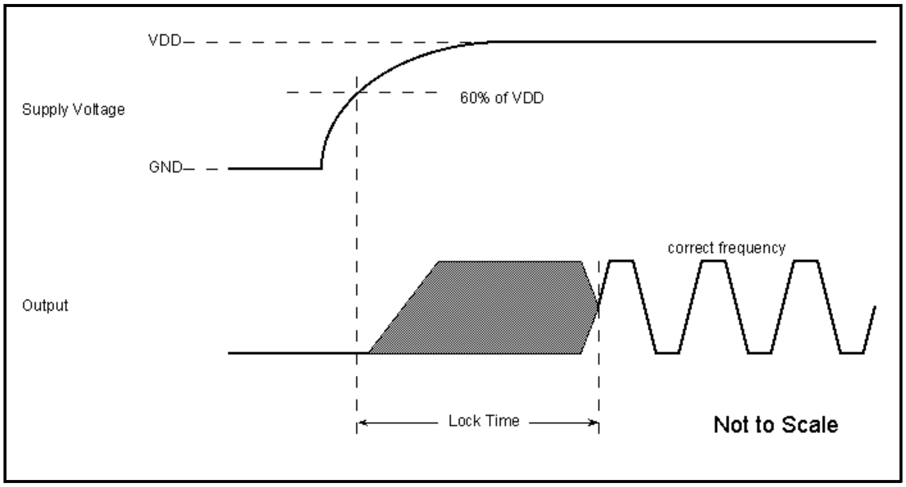


Output Rise/Fall Time



Output Duty Cycle/Pulse Width/Period

Parameter Measurement Information, continued



VCXO & FemtoClock PLL Lock Time

Application Information

Power Supply Filtering Technique

As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. The ICS810252DI-02 provides separate power supplies to isolate any high switching noise from the outputs to the internal PLL. V_{DD}, V_{DDA}, V_{DDO} and V_{DDX} should be individually connected to the power supply plane through vias, and 0.01µF bypass capacitors should be used for each pin. *Figure 1* illustrates this for a generic V_{DD} pin and also shows that V_{DDA} requires that an additional 10Ω resistor along with a 10µF bypass capacitor be connected to the V_{DDA} pin.

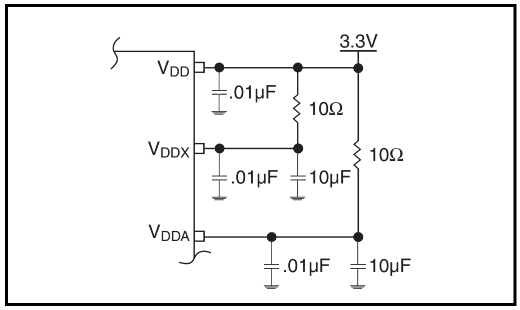


Figure 1. Power Supply Filtering

Wiring the Differential Input to Accept Single-Ended Levels

Figure 2 shows how a differential input can be wired to accept single ended levels. The reference voltage $V_{REF} = V_{DD}/2$ is generated by the bias resistors R1 and R2. The bypass capacitor (C1) is used to help filter noise on the DC bias. This bias circuit should be located as close to the input pin as possible. The ratio of R1 and R2 might need to be adjusted to position the V_{REF} in the center of the input voltage swing. For example, if the input clock swing is 2.5V and V_{DD} = 3.3V, R1 and R2 value should be adjusted to set V_{REF} at 1.25V. The values below are for when both the single ended swing and V_{DD} are at the same voltage. This configuration requires that the sum of the output impedance of the driver (Ro) and the series resistance (Rs) equals the transmission line impedance. In addition, matched termination at the input will attenuate the signal in half. This can be done in one of two ways. First, R3 and R4 in parallel should equal the transmission line impedance. For most 50Ω applications, R3 and R4 can be 100Ω. The values of the resistors can be increased to reduce the loading for slower and weaker LVCMOS driver. When using single ended signaling, the noise rejection benefits of differential signaling are reduced. Even though the differential input can handle full rail LVCMOS signaling, it is recommended that the amplitude be reduced. The datasheet specifies a lower differential amplitude, however this only applies to differential signals. For single-ended applications, the swing can be larger, however V_{IL} cannot be less than -0.3V and V_{IH} cannot be more than V_{DD} 0.3V. Though some of the recommended components might not be used, the pads should be placed in the layout. They can be utilized for debugging purposes. The datasheet specifications are characterized and guaranteed by using a differential signal.

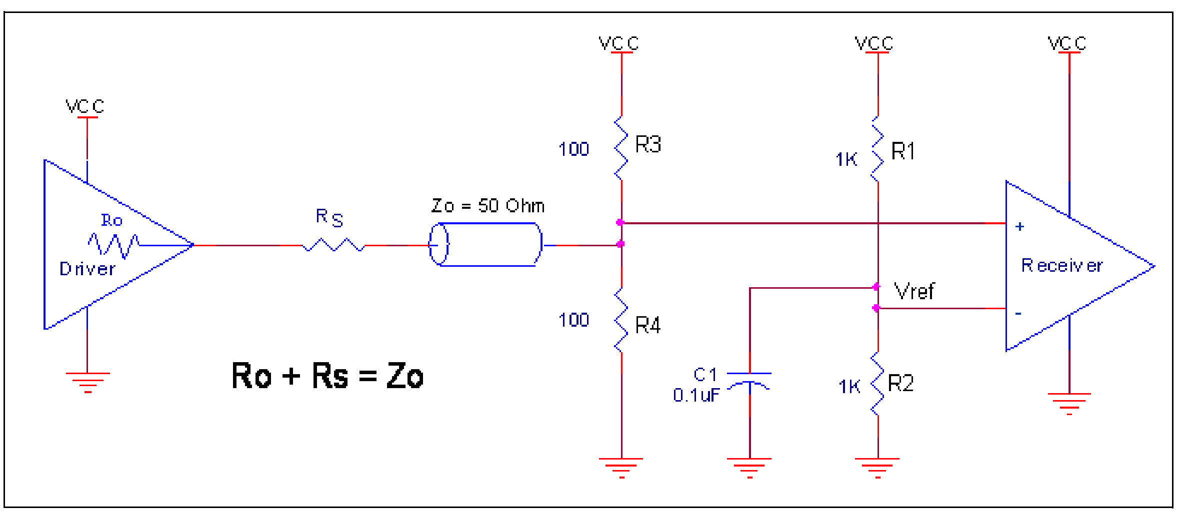


Figure 2. Recommended Schematic for Wiring a Differential Input to Accept Single-ended Levels

Differential Clock Input Interface

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both differential signals must meet the V_{PP} and V_{CMR} input requirements. *Figures 3A to 3F* show interface examples for the CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are examples only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example, in Figure 3A, the input termination applies for IDT open emitter LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

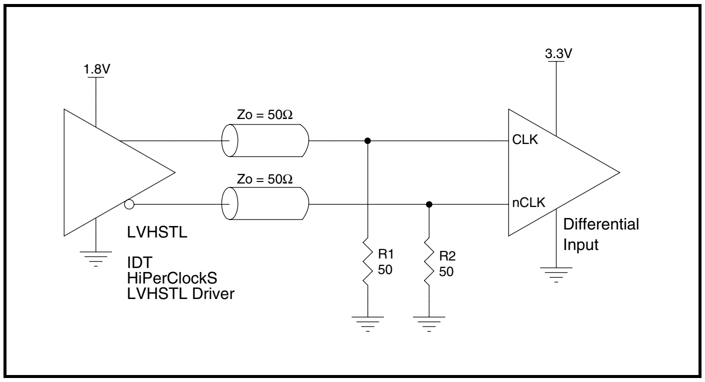


Figure 3A. CLK/nCLK Input Driven by an IDT Open Emitter LVHSTL Driver

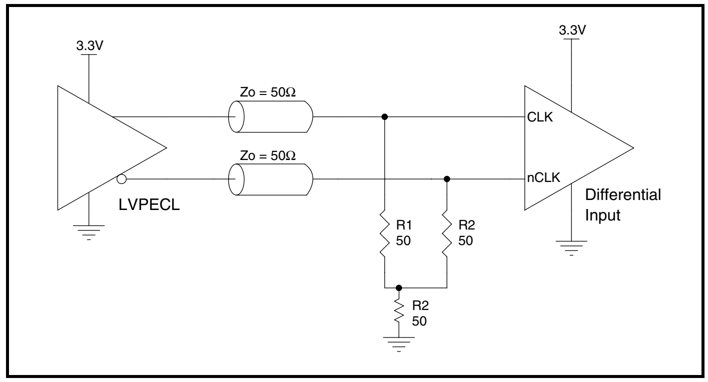


Figure 3B. CLK/nCLK Input Driven by a 3.3V LVPECL Driver

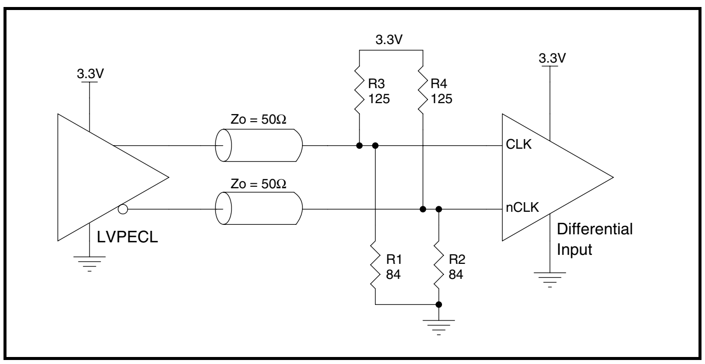


Figure 3C. CLK/nCLK Input Driven by a 3.3V LVPECL Driver

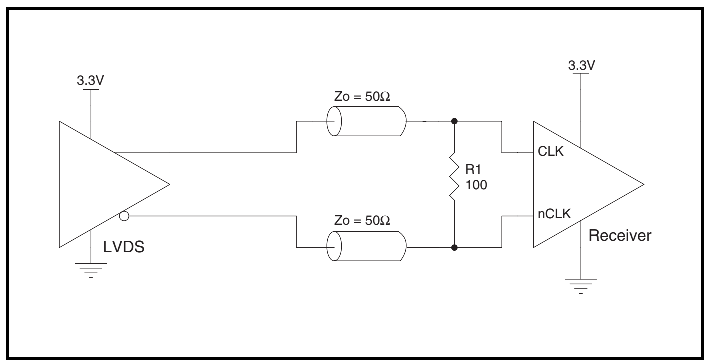


Figure 3D. CLK/nCLK Input Driven by a 3.3V LVDS Driver

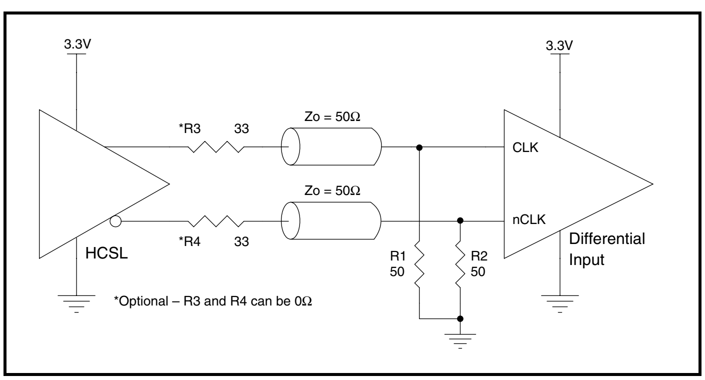


Figure 3E. CLK/nCLK Input Driven by a 3.3V HCSL Driver

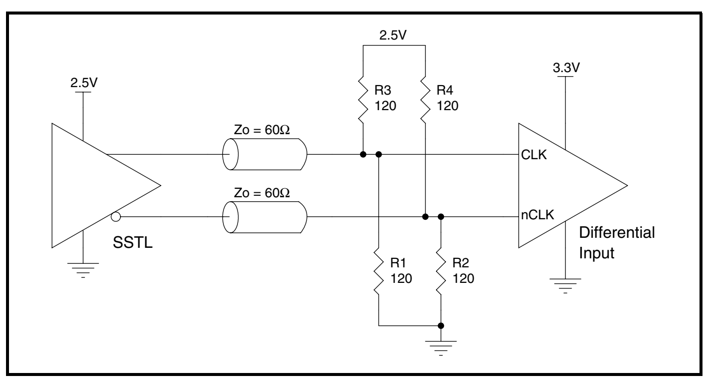


Figure 3F. CLK/nCLK Input Driven by a 2.5V SSTL Driver

Recommendations for Unused Input and Output Pins

Inputs:

CLK/nCLK Inputs

For applications not requiring the use of the differential input, both CLK and nCLK can be left floating. Though not required, but for additional protection, a 1kΩ resistor can be tied from CLK to ground.

LVCMOS Control Pins

All control pins have internal pullups or pulldowns; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

Outputs:

LVCMOS Outputs

All unused LVCMOS output can be left floating. There should be no trace attached.

VFQFN EPAD Thermal Release Path

In order to maximize both the removal of heat from the package and the electrical performance, a land pattern must be incorporated on the Printed Circuit Board (PCB) within the footprint of the package corresponding to the exposed metal pad or exposed heat slug on the package, as shown in *Figure 4.* The solderable area on the PCB, as defined by the solder mask, should be at least the same size/shape as the exposed pad/slug area on the package to maximize the thermal/electrical performance. Sufficient clearance should be designed on the PCB between the outer edges of the land pattern and the inner edges of pad pattern for the leads to avoid any shorts.

While the land pattern on the PCB provides a means of heat transfer and electrical grounding from the package to the board through a solder joint, thermal vias are necessary to effectively conduct from the surface of the PCB to the ground plane(s). The land pattern must be connected to ground through these vias. The vias act as “heat pipes”. The number of vias (i.e. “heat pipes”) are application specific and dependent upon the package power dissipation as well as electrical conductivity requirements. Thus, thermal and electrical analysis and/or testing are recommended to determine the minimum number needed. Maximum thermal and electrical performance is achieved when an array of vias is incorporated in the land pattern. It is recommended to use as many vias connected to ground as possible. It is also recommended that the via diameter should be 12 to 13mils (0.30 to 0.33mm) with 1oz copper via barrel plating. This is desirable to avoid any solder wicking inside the via during the soldering process which may result in voids in solder between the exposed pad/slug and the thermal land. Precautions should be taken to eliminate any solder voids between the exposed heat slug and the land pattern. Note: These recommendations are to be used as a guideline only. For further information, please refer to the Application Note on the Surface Mount Assembly of Amkor’s Thermally/ Electrically Enhance Leadframe Base Package, Amkor Technology.

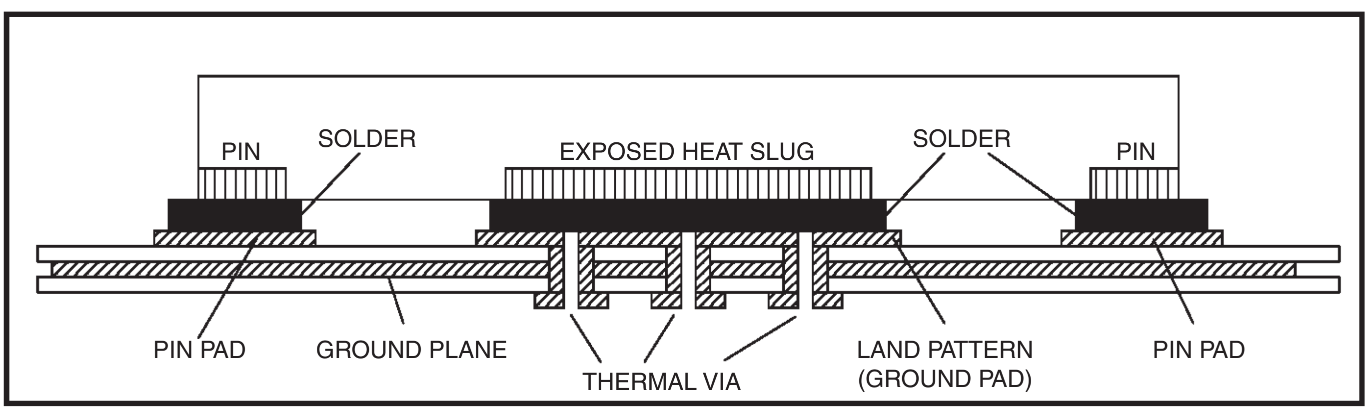


Figure 4. P.C. Assembly for Exposed Pad Thermal Release Path – Side View (drawing not to scale)

Schematic Example

Figure 5 shows an example of the 810252DI-02 application schematic. In this example, the device is operated at V_{DD} = 3.3V. The decoupling capacitors should be located as close as possible to the power pin. The input is driven by a 3.3V LVPECL driver. An optional 3-pole filter can also be used for additional spur reduction. It is recommended that the loop filter components be laid out for the 3-pole option. This will also allow the 2-pole filter to be used.

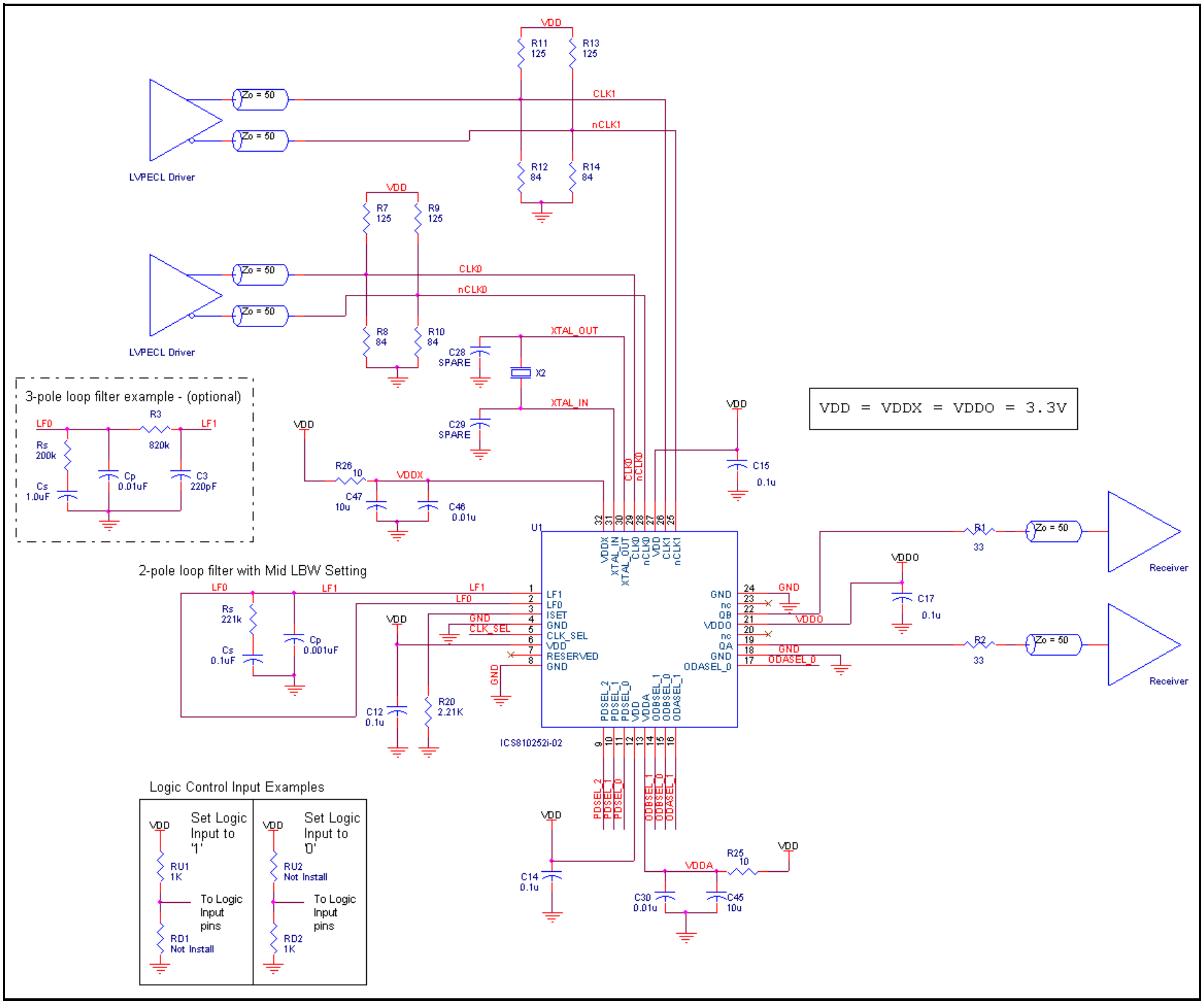


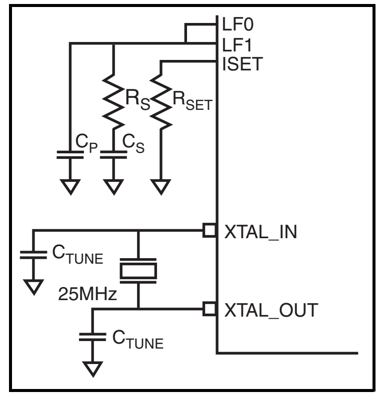
Figure 5. ICS810252DI-02 Schematic Example

VCXO-PLL External Components

Choosing the correct external components and having a proper printed circuit board (PCB) layout is a key task for quality operation of the VCXO-PLL. In choosing a crystal, special precaution must be taken with the package and load capacitance (C_L). In addition, frequency, accuracy and temperature range must also be considered. Since the pulling range of a crystal also varies with the package, it is recommended that a metal-canned package like HC49 be used. Generally, a metal-canned package has a larger pulling range than a surface mounted device (SMD). For crystal selection information, refer to the *VCXO Crystal Selection Application Note.*

The crystal's load capacitance C_L characteristic determines its resonating frequency and is closely related to the VCXO tuning range. The total external capacitance seen by the crystal when installed on a board is the sum of the stray board capacitance, IC package lead capacitance, internal varactor capacitance and any installed tuning capacitors (C_{TUNE}).

If the crystal's C_L is greater than the total external capacitance, the VCXO will oscillate at a higher frequency than the crystal specification. If the crystal's C_L is lower than the total external capacitance, the VCXO will oscillate at a lower frequency than the crystal specification. In either case, the absolute tuning range is reduced. The correct value of C_L is dependent on the characteristics of the VCXO. The recommended C_L in the Crystal Parameter Table balances the tuning range by centering the tuning curve.



The frequency of oscillation in the third overtone mode is not necessarily at exactly three times the fundamental frequency. The mechanical properties of the quartz element dictate the position of the overtones relative to the fundamental. The oscillator circuit may excite both the fundamental and overtone modes simultaneously. This will cause a nonlinearity in the tuning curve. This potential problem is why VCXO crystals are required to be tested for absence of any activity inside a ±200 ppm window at three times the fundamental frequency. Refer to F_{L_3OVT} and $F_{L\_3OVT\_spurs}$ in the crystal Characteristics table.

The crystal and external loop filter components should be kept as close as possible to the device. Loop filter and crystal traces should be kept short and separated from each other. Other signal traces should be kept separate and not run underneath the device, loop filter or crystal components.

VCXO Characteristics Table

Symbol	Parameter	Typical	Units
k_{VCXO}	VCXO Gain	16,700	kHz/V
C_{V_LOW}	Low Varactor Capacitance	9.8	pF
C_{V_HIGH}	High Varactor Capacitance	22.9	pF

VCXO-PLL Loop Bandwidth Selection Table

Bandwidth	Crystal Frequency (MHz)	R_S (kΩ)	C_S (µF)	C_P (µF)	R_{SET} (kΩ)
10Hz (Low)	25	121	1.0	0.01	9.09
90Hz (Mid)	25	221	0.1	0.001	2.21
300Hz (High)	25	680	0.1	0.0001	2.21

Crystal Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
	Mode of Oscillation			Fundamental		
f_N	Frequency			25		MHz
f_T	Frequency Tolerance				±20	ppm
f_S	Frequency Stability				±20	ppm
	Operating Temperature Range		-40		85	^{0}C
C_L	Load Capacitance			10		pF
C_O	Shunt Capacitance			4		pF
C_O / C_1	Pullability Ratio			220	240	
F_{L_3OVT}	3^{RD} Overtone F_L		200			ppm
$F_{L\_3OVT\_spurs}$	3^{RD} Overtone F_L Spurs		200			ppm
ESR	Equivalent Series Resistance				20	Ω
	Drive Level				1	mW
	Aging @ 25 ^{0}C				±3 per year	ppm

Reliability Information

Table 6. θ_{JA} vs. Air Flow Table for a 32 Lead VFQFN

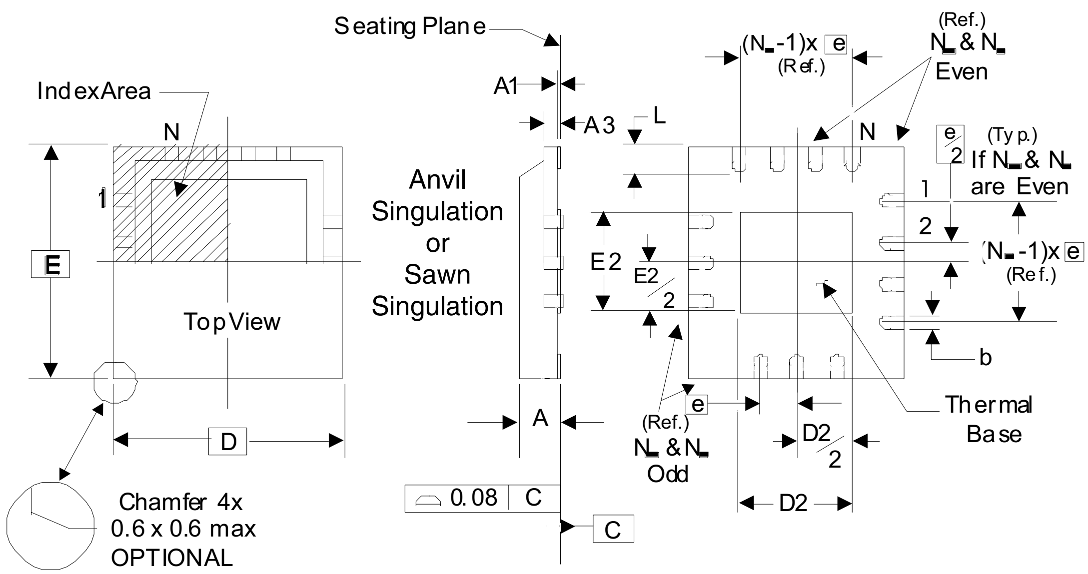
θ_{JA} vs. Air Flow			
Meters per Second	**0**	**1**	**2.5**
Multi-Layer PCB, JEDEC Standard Test Boards	37.0°C/W	32.4°C/W	29°C/W

Transistor Count

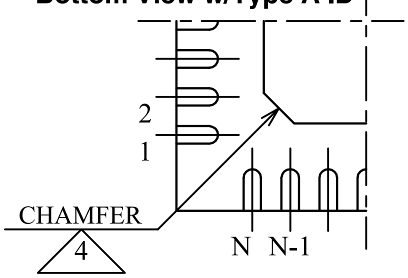
The transistor count for ICS810252DI-02 is: 6673

Package Outline and Package Dimensions

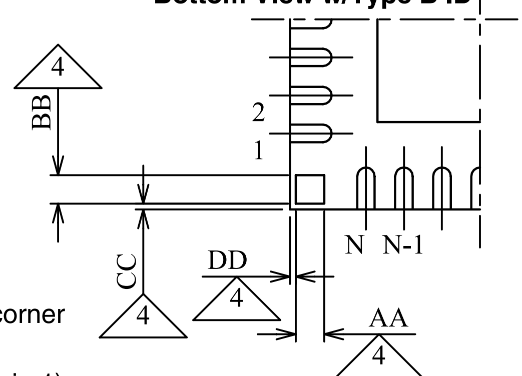
Package Outline - K Suffix for 32 Lead VFQFN



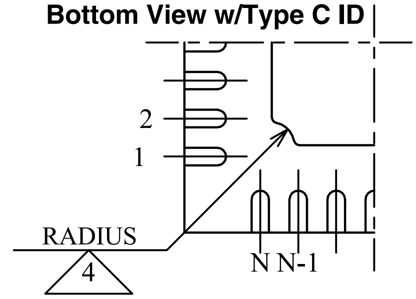
Bottom View w/Type A ID



Bottom View w/Type B ID



Bottom View w/Type C ID



There are 3 methods of indicating pin 1 corner at the back of the VFQFN package are:

1. Type A: Chamfer on the paddle (near pin 1)
2. Type B: Dummy pad between pin 1 and N.
3. Type C: Mouse bite on the paddle (near pin 1)

Table 7. Package Dimensions

JEDEC Variation: VHHD-2/-4 All Dimensions in Millimeters			
Symbol	**Minimum**	**Nominal**	**Maximum**
N		32	
A	0.80		1.00
A1	0		0.05
A3		0.25 Ref.	
b	0.18	0.25	0.30
N_D & N_E			8
D & E		5.00 Basic	
D2 & E2	3.0		3.3
e		0.50 Basic	
L	0.30	0.40	0.50

Reference Document: JEDEC Publication 95, MO-220

NOTE: The following package mechanical drawing is a generic drawing that applies to any pin count VFQFN package. This drawing is not intended to convey the actual pin count or pin layout of this device. The pin count and pinout are shown on the front page. The package dimensions are in Table 7.

Ordering Information

Table 8. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
810252DKI-02LF	ICS252DI02L	“Lead-Free” 32 Lead VFQFN	Tray	-40°C to 85°C
810252DKI-02LFT	ICS252DI02	“Lead-Free” 32 Lead VFQFN	2500 Tape & Reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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